

A1
cont
6. The method of claim 1 wherein an acrylate compound is added to the reaction mixture over the substantial course of the polymerization reaction.

A2
39. (amended) The method of claim 1 further comprising applying a coating layer of the photoresist composition on a substrate, exposing the photoresist coating layer to patterned activating radiation; and developing the exposed photoresist coating layer to provide a resist relief image.

A3
82. (amended) A method of forming a photoresist relief image, comprising:
(a) applying a coating layer of a photoresist of claim 44 on a substrate; and
(b) exposing and developing the photoresist layer to yield a relief image.

A4
86. (amended) An article of manufacture comprising a microelectronic wafer substrate or flat panel display substrate having coated thereon a layer of the photoresist composition of claim 44.

A5
123. (amended) A polymer obtained by a method of claim 88.

REMARKS

For the sole purpose of reducing initial filing fees, claims 7-38, 43, 46-81, and 90-122 have been cancelled without prejudice, and claims 3, 4-6, 39, 82, 86 and 123 have been amended to remove multiple dependencies. Applicants reserve all rights to pursue the subject matter of the cancelled claims and amended claims in the present or suitable continuing application.

Early consideration and allowance of the application are earnestly solicited.